




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	FR-4	5.12mil	4.2	
2	Signal Layer 1	Copper	1.38mil		
	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	FR-4	5.12mil	4.2	
2	Signal Layer 1	Copper	1.38mil		
	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	FR-4	5.12mil	4.2	
2	Signal Layer 1	Copper	1.38mil		
	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
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3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				



	Material	Thickness	Constant	Board
	Solder Resist	0.51mil	3.3	
	Copper	1.38mil		
	FR-4	5.12mil	4.2	
Layer 1	Copper	1.38mil		
Layer 2	FR-4	47.24mil	4.2	
Layer 2	Copper	1.38mil		
Layer 3	FR-4	5.12mil	4.2	
Layer 4	Copper	1.38mil		
Layer 5	Solder Resist	0.51mil	3.3	
Total Layer				


GND

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	FR-4	5.12mil	4.2	
2	Signal Layer 1	Copper	1.38mil		
	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	FR-4	5.12mil	4.2	
2	Signal Layer 1	Copper	1.38mil		
	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				

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3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				



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	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
1	Top Solder	Solder Resist	0.51mil	3.3	
1	Top Layer	Copper	1.38mil		
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2	Dielectric 2	FR-4	47.24mil	4.2	
3	Signal Layer 2	Copper	1.38mil		
3	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
4	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				

Layer	Name	Material	Thickness	Constant	Board Layer Stack
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3	Signal Layer 2	Copper	1.38mil		
	Dielectric 3	FR-4	5.12mil	4.2	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
○	2	0.500mm (19.69mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r90_160h50_120r100				1.200mm (47.24mil)	0.700mm (27.56mil)
□	2	0.550mm (21.65mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r125_95h55_85r100				0.850mm (33.47mil)	0.300mm (11.81mil)
◊	4	4.500mm (177.17mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h450				-	-
▼	6	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v80h40m0mx0				-	-
✖	6	1.900mm (74.80mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c300h190				-	-
◇	8	1.700mm (66.93mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c240h170				-	-
☒	32	1.800mm (70.87mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c250h180				-	-
○	38	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h320				-	-
□	40	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
▽	740	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
❖	1007	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
1885 Total													

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
1	Top Solder	Solder Resist	0.51mil	3.3	
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	Bottom Overlay				



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4	Bottom Layer	Copper	1.38mil		
4	Bottom Solder	Solder Resist	0.51mil	3.3	
	Bottom Overlay				